

74LV14A

Hex inverting Schmitt trigger

Rev. 1 — 13 June 2016

Product data sheet

1. General description

The 74LV14A is a hexadecimal inverter with Schmitt-trigger inputs, capable of transforming slowly changing input signals into sharply defined, jitter-free output signals.

Inputs are overvoltage tolerant. This feature allows the use of these devices as translators in mixed voltage environments.

This device is fully specified for partial power down applications using I_{OFF} . The I_{OFF} circuitry disables the output, preventing the potentially damaging backflow current through the device when it is powered down.

2. Features and benefits

- Wide supply voltage range from 2.0 V to 5.5 V
- Maximum t_{pd} of 10 ns at 5 V
- Typical $V_{OL(p)} < 0.8$ V at $V_{CC} = 3.3$ V, $T_{amb} = 25$ °C
- Typical $V_{OH(v)} > 2.3$ V at $V_{CC} = 3.3$ V, $T_{amb} = 25$ °C
- Supports mixed-mode voltage operation on all ports
- I_{OFF} circuitry provides partial Power-down mode operation
- Latch-up performance exceeds 250 mA per JESD 78 Class II
- ESD protection:
 - ◆ HBM ANSI/ESDA/JEDEC JS-001 Class 2 exceeds 3 kV
 - ◆ MM JESD22-A115-A exceeds 200 V
 - ◆ CDM JESD22-C101E exceeds 2 kV
- Multiple package options
- Specified from -40 °C to $+85$ °C and from -40 °C to $+125$ °C

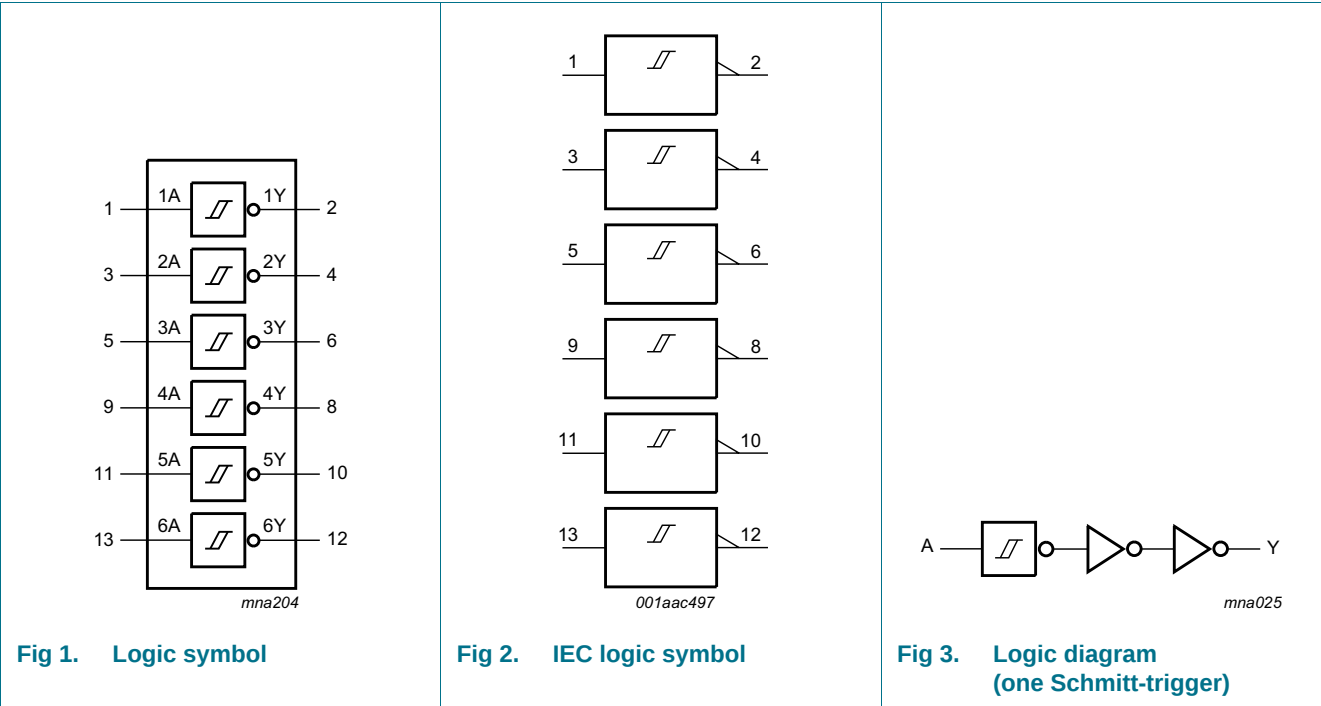
3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74LV14AD	-40 °C to $+125$ °C	SO14	plastic small outline package; 14 leads; body width 3.9 mm	SOT108-1
74LV14APW	-40 °C to $+125$ °C	TSSOP14	plastic thin shrink small outline package; 14 leads; body width 4.4 mm	SOT402-1
74LV14ABQ	-40 °C to $+125$ °C	DHVQFN14	plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body $2.5 \times 3 \times 0.85$ mm	SOT762-1

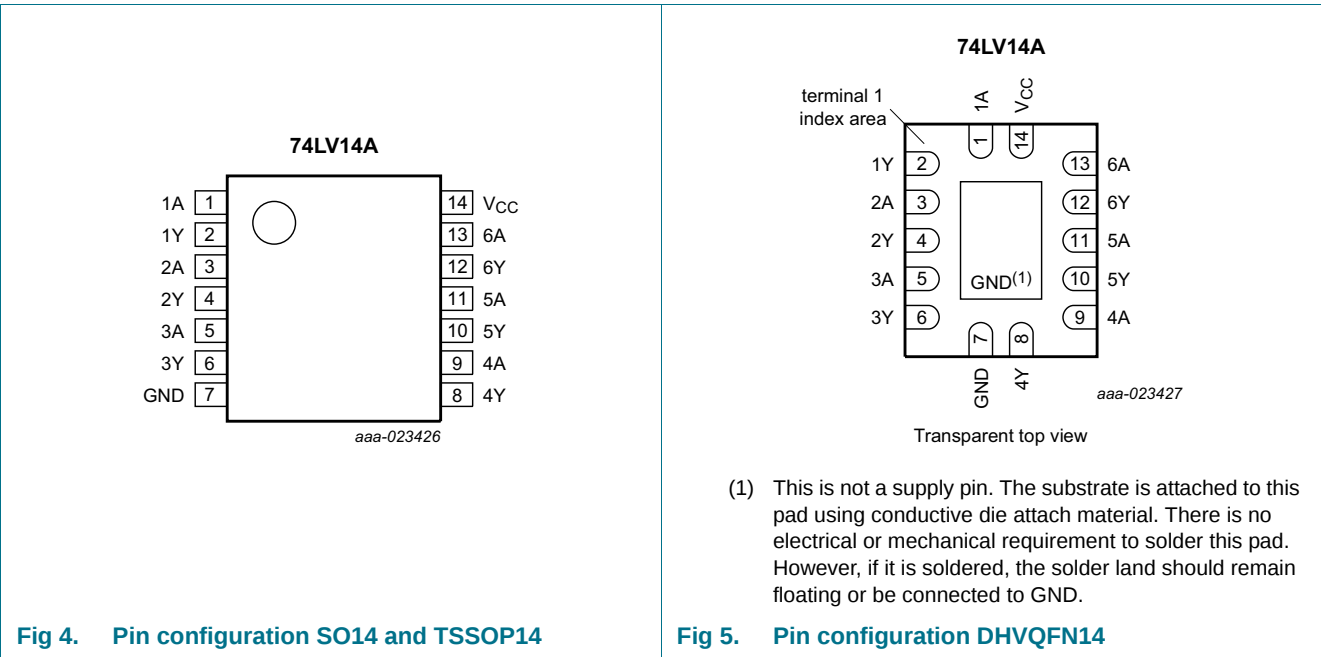


4. Functional diagram



5. Pinning information

5.1 Pinning



5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
1A, 2A, 3A, 4A, 5A, 6A	1, 3, 5, 9, 11, 13	data input
1Y, 2Y, 3Y, 4Y, 5Y, 6Y	2, 4, 6, 8, 10, 12	data output
GND	7	ground (0 V)
V _{CC}	14	supply voltage

6. Functional description

Table 3. Function table^[1]

Input	Output
nA	nY
L	H
H	L

- [1] H = HIGH voltage level;
L = LOW voltage level.

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	supply voltage		-0.5	+7.0	V
V _I	input voltage		-0.5	+7.0	V
V _O	output voltage	output HIGH or LOW state	-0.5	V _{CC} + 0.5	V
		output power-down	-0.5	+7.0	V
I _{IK}	input clamping current	V _I < 0 V	-20	-	mA
I _{OK}	output clamping current	V _O < 0 V	-50	-	mA
I _O	output current	V _O = 0 V to V _{CC}	-	±35	mA
I _{CC}	supply current		-	70	mA
I _{GND}	ground current		-70	-	mA
T _{stg}	storage temperature		-65	+150	°C
P _{tot}	total power dissipation	T _{amb} = -40 °C to +125 °C	-	500	mW

- [1] If the input current ratings are observed, the minimum input voltage ratings may be exceeded.
 [2] If the output current ratings are observed, the output voltage ratings may be exceeded.
 [3] This value is limited to 7 V maximum.
 [4] For SO14 packages: above 95 °C, the value of P_{tot} derates linearly at 9 mW/K.
 For TSSOP14 packages: above 75 °C, the value of P_{tot} derates linearly at 7 mW/K.
 For DHVQFN14 packages: above 95 °C, the value of P_{tot} derates linearly at 9.3 mW/K.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CC}	supply voltage		2.0	5.0	5.5	V
V_I	input voltage		0	-	5.5	V
V_O	output voltage	output HIGH or LOW state	0	-	V_{CC}	V
		output power-down	0	-	5.5	V
T_{amb}	ambient temperature		-40	+25	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	-	-	50	ms/V
		$V_{CC} = 3.0 \text{ V to } 3.6 \text{ V}$	-	-	20	ms/V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	-	-	1	ms/V

9. Static characteristics

Table 6. Static characteristics

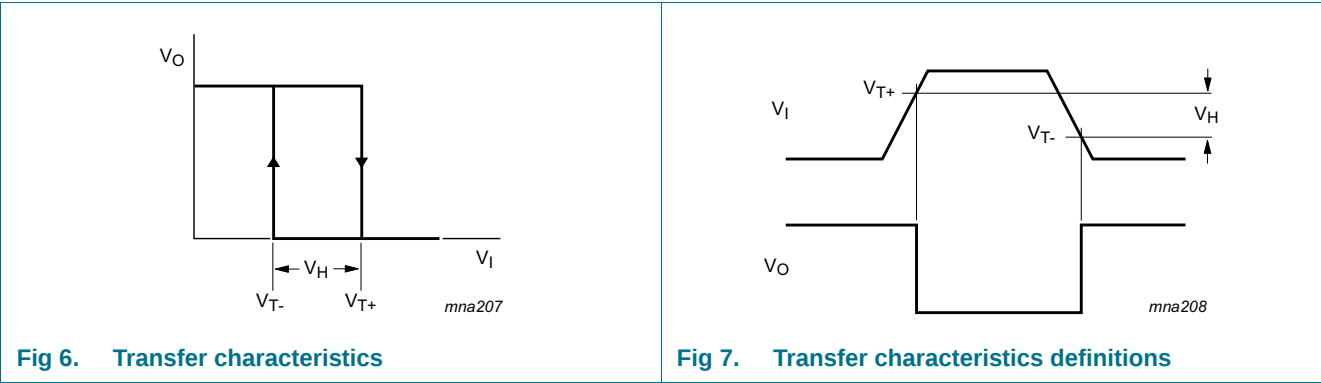
Voltages are referenced to GND (ground = 0 V).

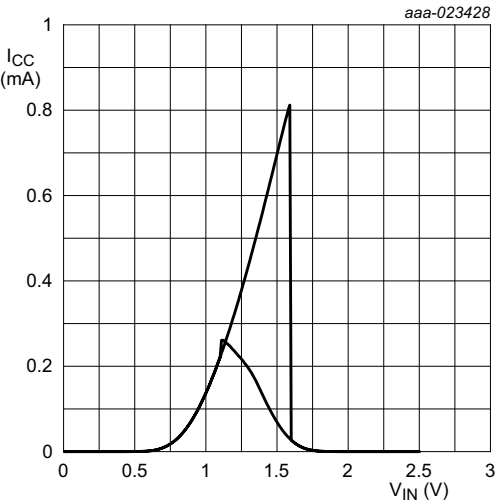
Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
V_{T+}	positive-going threshold voltage	$V_{CC} = 2.5 \text{ V}$	-	-	1.75	-	1.75	-	1.75	V
		$V_{CC} = 3.3 \text{ V}$	-	-	2.31	-	2.31	-	2.31	V
		$V_{CC} = 5.0 \text{ V}$	-	-	3.5	-	3.5	-	3.5	V
V_{T-}	negative-going threshold voltage	$V_{CC} = 2.5 \text{ V}$	0.75	-	-	0.75	-	0.75	-	V
		$V_{CC} = 3.3 \text{ V}$	0.99	-	-	0.99	-	0.99	-	V
		$V_{CC} = 5.0 \text{ V}$	1.5	-	-	1.5	-	1.5	-	V
V_H	hysteresis voltage	$V_{CC} = 2.5 \text{ V}$	0.25	-	-	0.25	-	0.25	-	V
		$V_{CC} = 3.3 \text{ V}$	0.33	-	-	0.33	-	0.33	-	V
		$V_{CC} = 5.0 \text{ V}$	0.5	-	-	0.5	-	0.5	-	V
V_{OH}	HIGH-level output voltage	$V_I = V_{IH} \text{ or } V_{IL}$								
		$V_{CC} = 2.0 \text{ V to } 5.5 \text{ V}; I_O = -50 \mu\text{A}$	$V_{CC}-0.1$	-	-	$V_{CC}-0.1$	-	$V_{CC}-0.1$	-	V
		$V_{CC} = 2.3 \text{ V}; I_O = -2 \text{ mA}$	2	-	-	2	-	2	-	V
		$V_{CC} = 3.0 \text{ V}; I_O = -6 \text{ mA}$	2.48	-	-	2.48	-	2.48	-	V
		$V_{CC} = 4.5 \text{ V}; I_O = -12 \text{ mA}$	3.8	-	-	3.8	-	3.8	-	V
V_{OL}	LOW-level output voltage	$V_I = V_{IH} \text{ or } V_{IL}$								
		$V_{CC} = 2.0 \text{ V to } 5.5 \text{ V}; I_O = 50 \mu\text{A}$	-	-	0.1	-	0.1	-	0.1	V
		$V_{CC} = 2.3 \text{ V}; I_O = 2 \text{ mA}$	-	-	0.4	-	0.4	-	0.4	V
		$V_{CC} = 3.0 \text{ V}; I_O = 6 \text{ mA}$	-	-	0.44	-	0.44	-	0.44	V
		$V_{CC} = 4.5 \text{ V}; I_O = 12 \text{ mA}$	-	-	0.55	-	0.55	-	0.55	V

Table 6. Static characteristics ...continued
Voltages are referenced to GND (ground = 0 V).

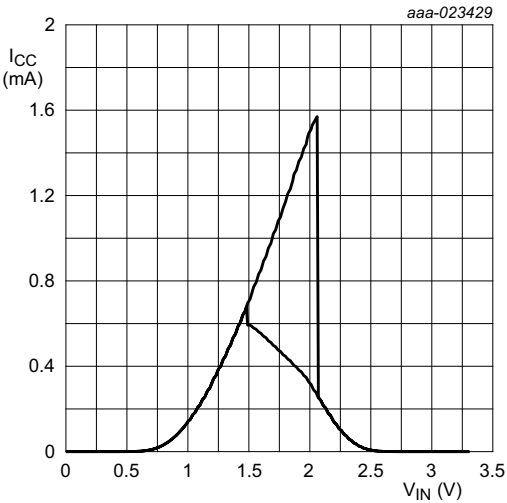
Symbol	Parameter	Conditions	25 °C			−40 °C to +85 °C		−40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
I _{OFF}	power-off leakage current	V _I or V _O = GND to 5.5 V; V _{CC} = 0 V	-	-	0.5	-	5	-	5	μA
I _I	input leakage current	V _I = V _{CC} or GND; V _{CC} = 0 V to 5.5 V	-	-	±0.1	-	±1	-	±1	μA
I _{CC}	supply current	V _I = V _{CC} or GND; I _O = 0 A; V _{CC} = 5.5 V	-	-	2	-	20	-	20	μA

9.1 Transfer characteristics waveforms

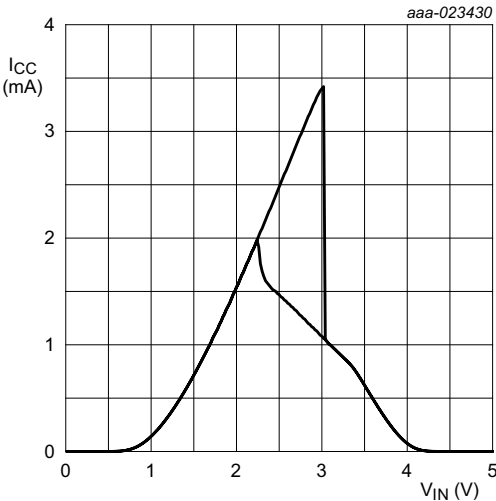




a. $V_{CC} = 2.5$ V



b. $V_{CC} = 3.3$ V



c. $V_{CC} = 5.0$ V

Fig 8. Typical transfer characteristics

10. Dynamic characteristics

Table 7. Dynamic characteristics
GND = 0 V. For test circuit, see [Figure 10](#).

Symbol	Parameter	Conditions	25 °C			–40 °C to +85 °C		–40 °C to +125 °C		Unit
			Min	Typ ^[1]	Max	Min	Max	Min	Max	
t _{pd}	propagation delay	nA to nY; see Figure 9 ^[2]								
		V _{CC} = 2.3 V to 2.7 V								
		C _L = 15 pF	-	5.6	19.7	1	22	1	23	ns
		C _L = 50 pF	-	8.7	24	1	27	1	28	ns
		V _{CC} = 3.0 V to 3.6 V								
		C _L = 15 pF	-	4.4	12.8	1	15	1	16	ns
		C _L = 50 pF	-	6.7	16.3	1	18.5	1	19.5	ns
		V _{CC} = 4.5 V to 5.5 V								
		C _L = 15 pF	-	3.4	8.6	1	10	1	11	ns
		C _L = 50 pF	-	5.2	10.6	1	12	1	13	ns
C _I	input capacitance	V _I = V _{CC} or GND; V _{CC} = 3.3 V	-	2	6	-	6	-	6	pF
C _O	output capacitance	V _O = V _{CC} or GND; V _{CC} = 3.3 V	-	5	-	-	-	-	-	pF
C _{PD}	power dissipation capacitance	per buffer; ^[3] C _L = 50 pF; f = 10 MHz; V _I = GND to V _{CC}								
		V _{CC} = 3.3 V	-	8	-	-	-	-	-	pF
		V _{CC} = 5.0 V	-	9	-	-	-	-	-	pF

[1] Typical values are measured at T_{amb} = 25 °C and V_{CC} = 2.5 V, 3.3 V, and 5 V respectively, unless otherwise specified.

[2] t_{pd} is the same as t_{PLH} and t_{PHL}.

[3] C_{PD} is used to determine the dynamic power dissipation P_D (μW).

$P_D = C_{PD} \times V_{CC}^2 \times f_i + \sum (C_L \times V_{CC}^2 \times f_o)$ where:

f_i = input frequency in MHz;

f_o = output frequency in MHz;

C_L = output load capacitance in pF;

V_{CC} = supply voltage in Volts.

Table 8. Noise characteristics
GND = 0 V. For test circuit, see Figure 10.

Symbol	Parameter	Conditions	T _{amb} = 25 °C			Unit
			Min	Typ	Max	
V _{CC} = 3.3 V; C _L = 50 pF						
V _{OL(p)}	LOW-level output voltage (peak)		-	0.2	0.8	V
V _{OL(v)}	LOW-level output voltage (valley)		−0.8	−0.1	-	V
V _{OH(v)}	HIGH-level output voltage (valley)		-	3.1	-	V
V _{IH(AC)}	AC HIGH-level input voltage		2.31	-	-	V
V _{IL(AC)}	AC LOW-level input voltage		-	-	0.99	V

11. Waveforms

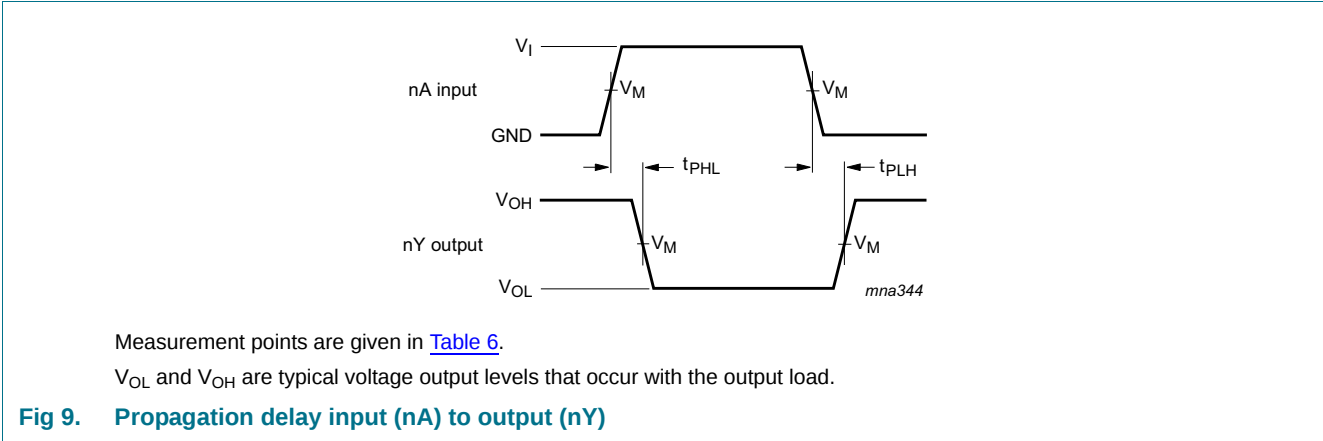
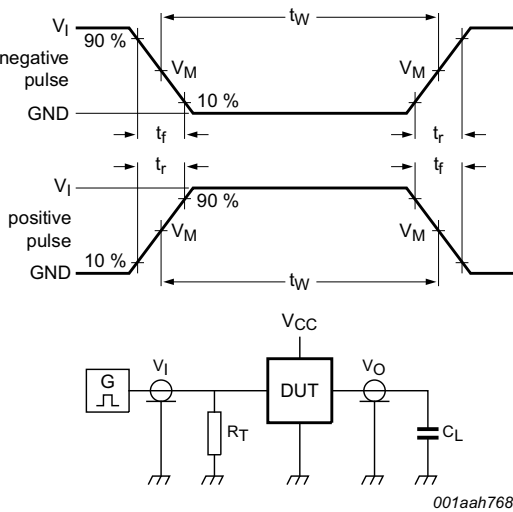


Table 9. Measurement points

Input	Output
V _M	V _M
0.5V _{CC}	0.5V _{CC}



Test data is given in [Table 10](#).
Definitions test circuit:
 R_T = Termination resistance should be equal to output impedance Z_o of the pulse generator
 C_L = Load capacitance including jig and probe capacitance
 $S1$ = Test selection switch

Fig 10. Test circuit for measuring switching times

Table 10. Test data

Input		Load	Test
V_I	t_r, t_f	C_L	
GND to V_{CC}	3.0 ns	15 pF, 50 pF	t_{PLH}, t_{PHL}

12. Package outline

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1

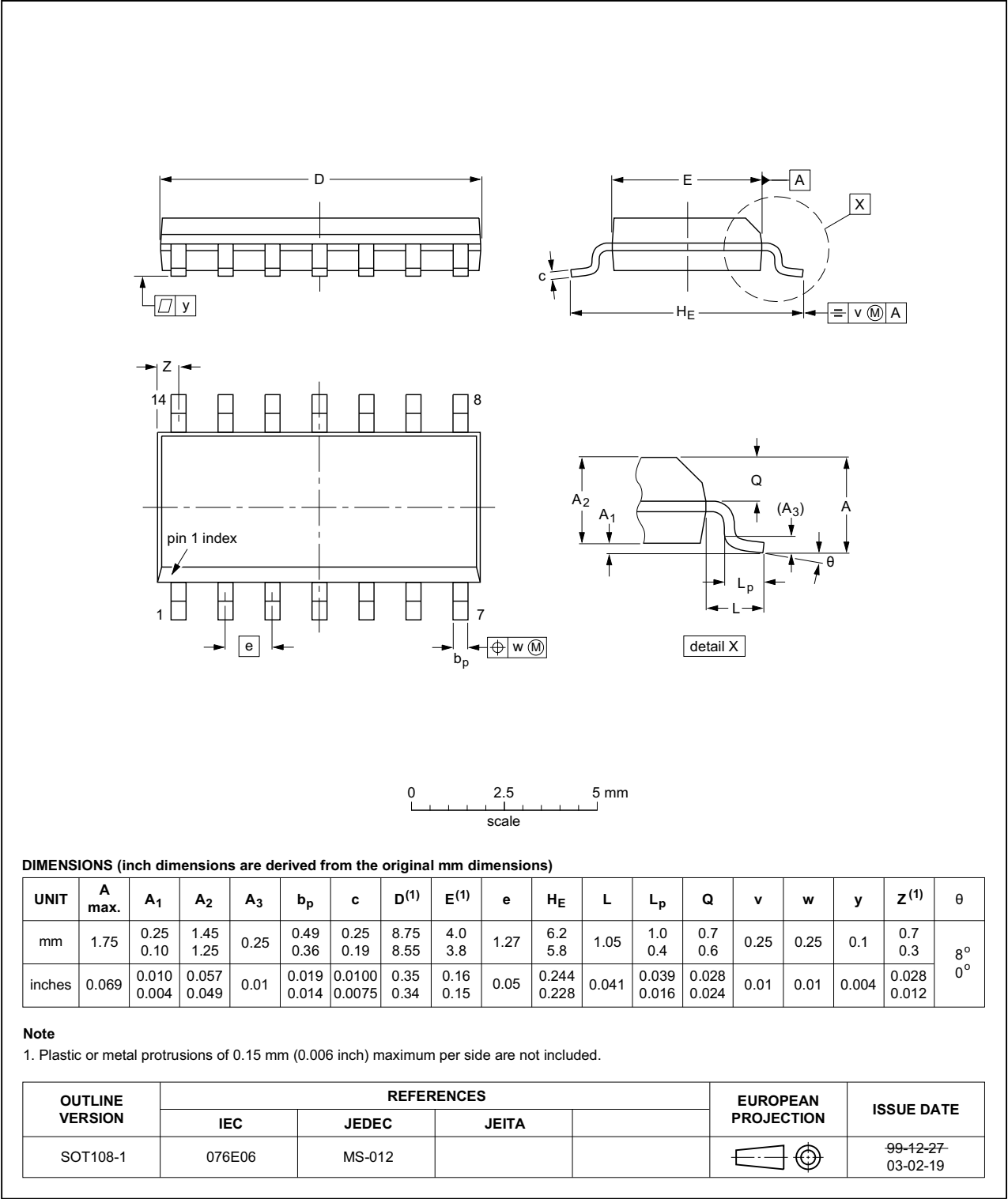


Fig 11. Package outline SOT108-1 (SO14)

TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

SOT402-1

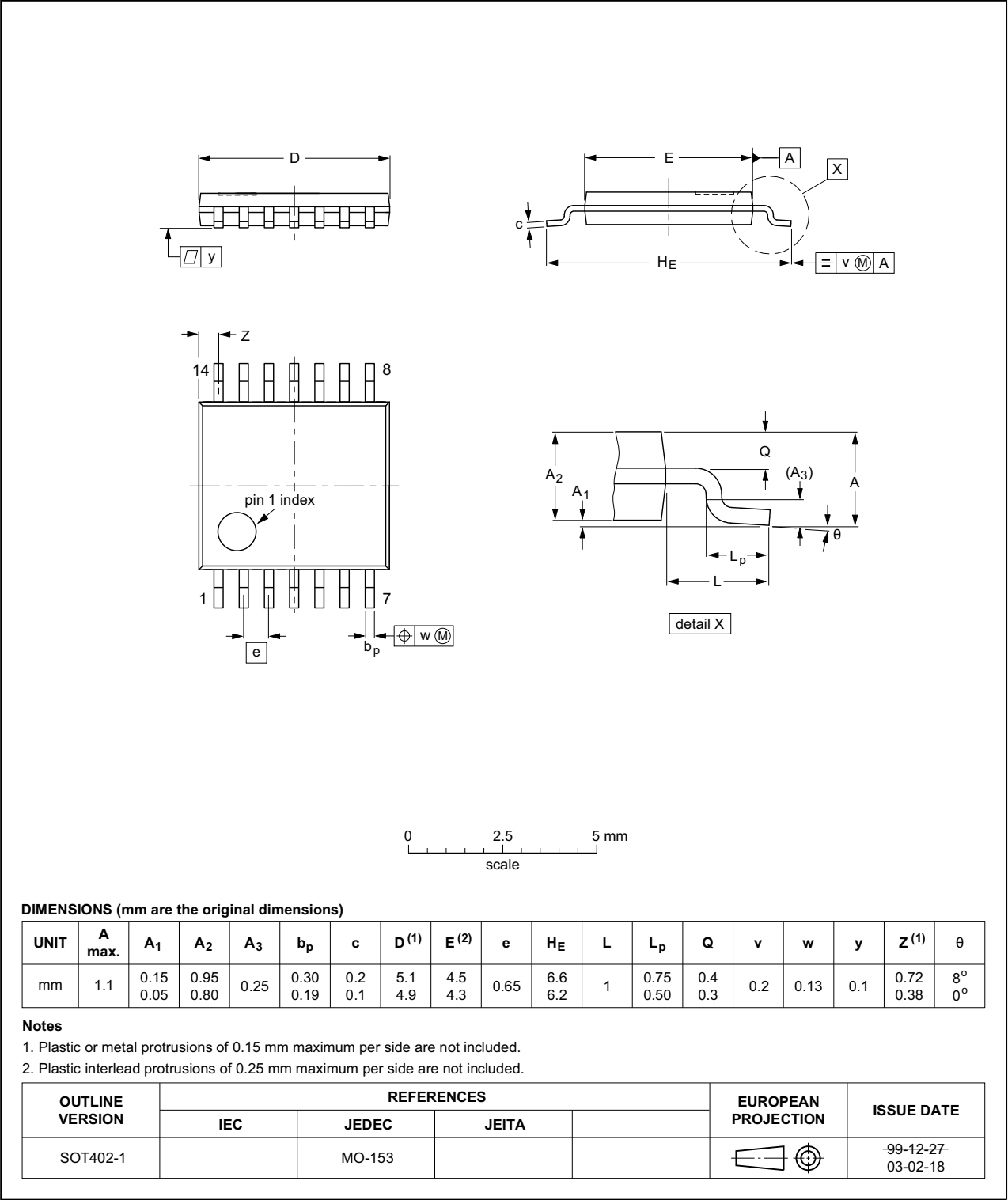


Fig 12. Package outline SOT402-1 (TSSOP14)

DHVQFN14: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads;
14 terminals; body 2.5 x 3 x 0.85 mm

SOT762-1

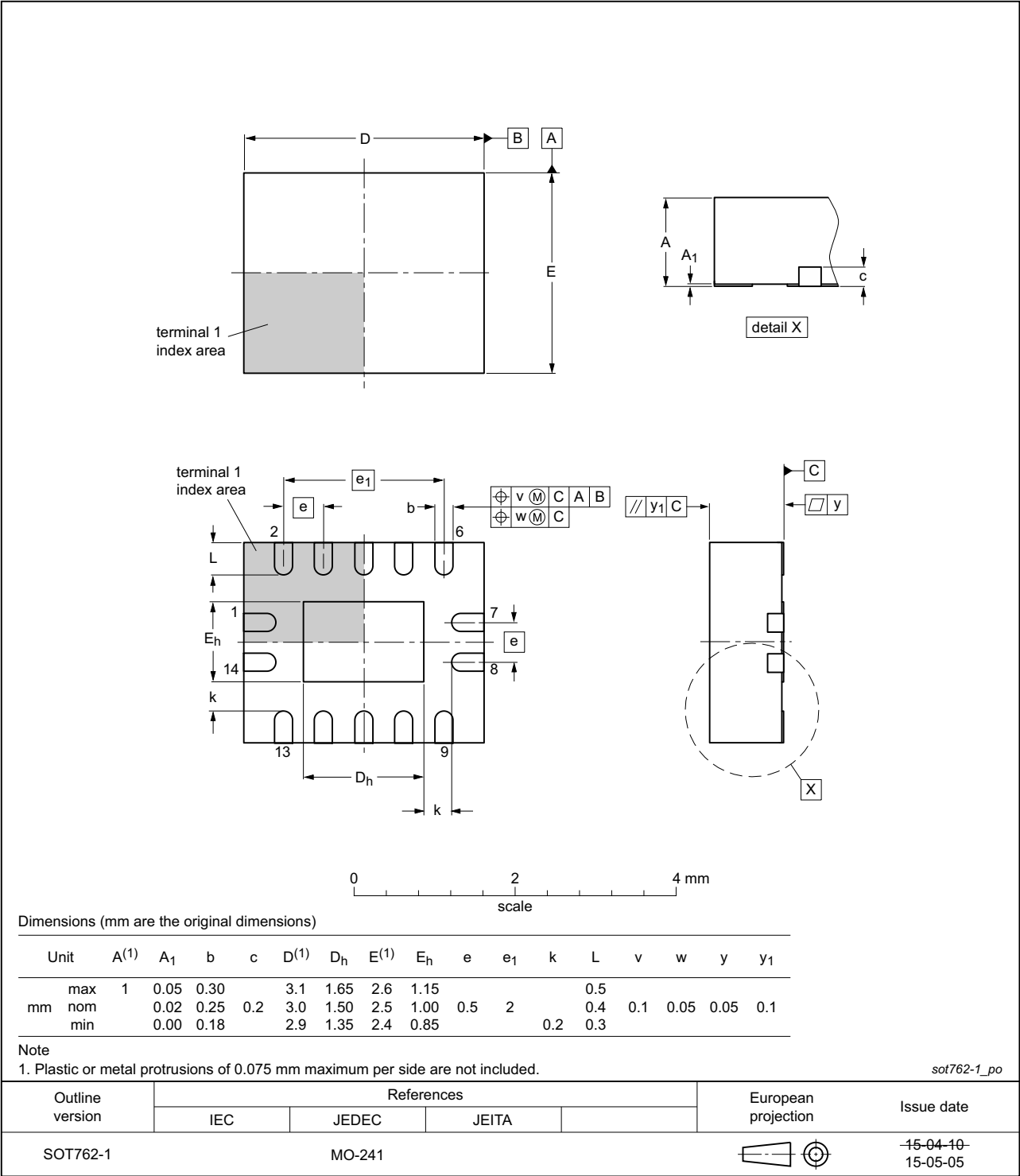


Fig 13. Package outline SOT762-1 (DHVQFN14)

13. Abbreviations

Table 11. Abbreviations

Acronym	Description
CDM	Charge Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model

14. Revision history

Table 12. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74LV14A v.1	20160613	Product data sheet	-	-

15. Legal information

15.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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17. Contents

1	General description	1
2	Features and benefits	1
3	Ordering information	1
4	Functional diagram	2
5	Pinning information	2
5.1	Pinning	2
5.2	Pin description	3
6	Functional description	3
7	Limiting values	3
8	Recommended operating conditions	4
9	Static characteristics	4
9.1	Transfer characteristics waveforms	5
10	Dynamic characteristics	7
11	Waveforms	8
12	Package outline	10
13	Abbreviations	13
14	Revision history	13
15	Legal information	14
15.1	Data sheet status	14
15.2	Definitions	14
15.3	Disclaimers	14
15.4	Trademarks	15
16	Contact information	15
17	Contents	16

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